

ABSTRACT OF THE DISCLOSURE

A new method has been developed to provide underfill to chips
5 mounted on substrates. First, an underfill is dispensed on the
substrate. Second, the bumps of the chip are dipped in a flux
that does not contain filler. Third, the chip that has been
dipped in a tacky thermosettable flux is placed on the substrate,
and fourth, the chip is soldered to the substrate, and
10 simultaneously the underfill is cured. This process eliminates
the interference on solder joints caused by the presence of filler
in filled no-flow underfill. In addition, the fluxing property of
the flux allows the use of underfills with emphasis on curing and
mechanical properties instead of fluxing performance. Accordingly,
15 a mounted device with reliable solder joints and underfill
encapsulation is obtained.

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